

IN THE SPECIFICATION

Please amend the paragraph beginning at page 17, line 3, as follows:

The cleaning liquid pouring nozzle 51 is not limited to such as provided with the cleaning liquid discharge slit 51a of a length equal to or greater than the diameter of the wafer W. A cleaning liquid pouring nozzle [[51]] 151 provided with a cleaning liquid discharge slit [[51a]] 151a of a length in the range of 8 to 15 mm as shown in Fig. 8(a) may be used instead [[o]] of the cleaning liquid pouring nozzle 51. When the cleaning liquid pouring nozzle [[51]] 151 shown in Fig. 8(a) is employed, the cleaning liquid pouring nozzle [[51]] 151 is moved radially from a position corresponding to the circumference of the wafer W toward a position corresponding to the center of the wafer W while the wafer W is being rotated about a vertical axis by the spin chuck 4 to pour the cleaning liquid spirally on the surface of the wafer W as shown in Fig. 8(b). After the cleaning liquid pouring nozzle [[51]] 151 has reached the position corresponding to the center of the wafer W, the liquid pouring nozzle [[51]] 151 may be moved radially outward from the position corresponding to the center of the wafer W. The operation for moving the cleaning liquid pouring nozzle radially inward and radially outward may be repeated several times. The cleaning liquid pouring nozzle [[51]] 151 may be provided with discharge openings of a small diameter instead of the discharge slit [[51a]] 151a.